# Datacon 2200 evo*plus*

## Innovative Solution for Innovative Products

The Datacon 2200 evo*plus* die bonder for Multi Module Attach assembles all kinds of technologies on a tried-and-tested platform, enhanced with key features for higher bonding accuracy and lower cost of ownership.

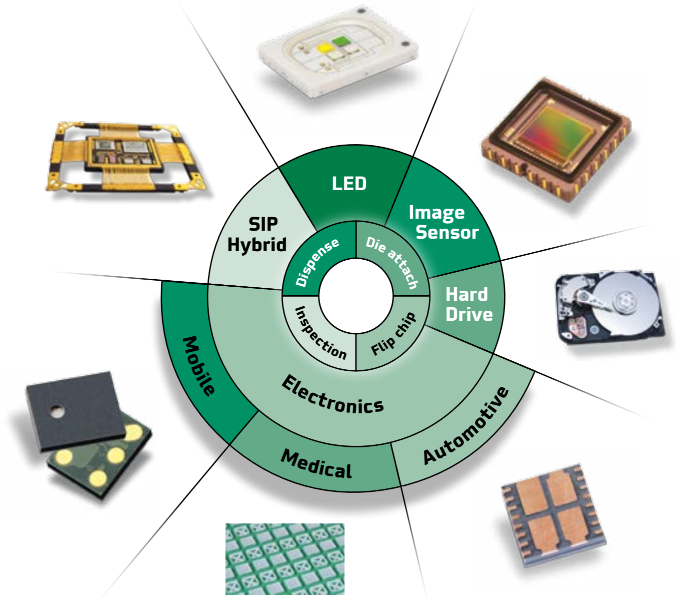
Besides unbeaten flexibility and full customization possibilities, this evolutionary machine offers higher accuracy with long-term stability using a new camera system and thermal compensation algorithm, higher speed through a new image processing unit, and improved cleanroom capabilities.

### Datacon 2200 evo goes *PLUS!*

**Enhancements**
- PLUS Accuracy
- PLUS Productivity
- PLUS Flexibility

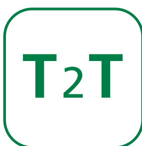
**Features**
- Multi-Chip Capability
- Flexibility for Customizing
- Open Platform Architecture

Future Proof Equipment

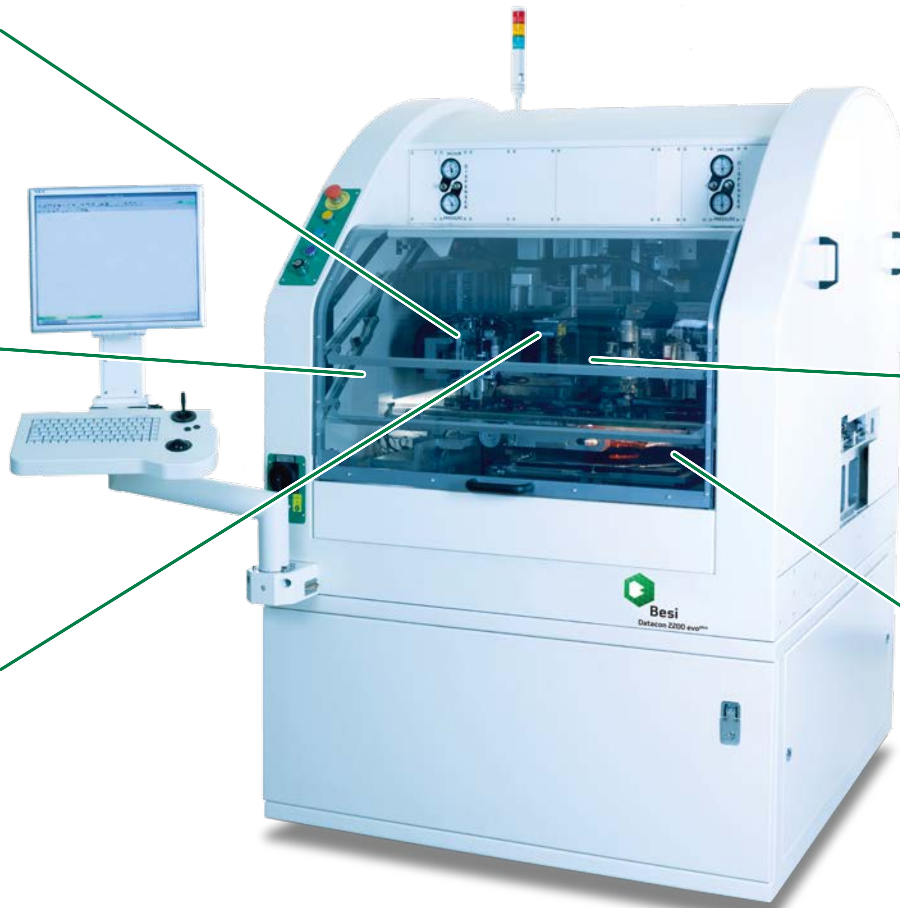



8 WEEKS LEAD TIME

TOOL-TO-TOOL REPEATABILITY

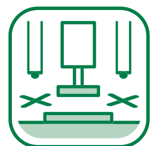



FLEXIBILITY



ACCURACY

MULTI-CHIP



www.besi.com - sales@besi.com

Besi

## Multi-Chip

- Fully automatic cycle for Multi-Chip production
- Up to 7 Pick & Place tools (optionally 14), 5 eject tools
- Pressure/time (Musashi®), Auger, Jetter type dispensers available
- Epoxy stamping option
- Filled and unfilled epoxy, wide viscosity range

## Accuracy

- New high-speed image processing unit
- Full alignment & Bad mark search
- Pre-defined fiducial geometry & customized teaching

7µ

## Pick & Place Head

- Die Attach, Flip Chip and Multi-Chip in one machine
- Die pick from: wafer, waffle pack, Gel-Pak®, feeder
- Die place to: substrate, boat, carrier, PCB, leadframe, wafer
- Hot and cold processes supported: epoxy, soldering, thermo-compression, eutectic

Factory Integration
SCT
SECS GEM
E142
Material Supply
Substrate
Strip
Panel
Leadframe
PCB
Wafer
Components
Tape Reel
Bowl Freeder
Gel Pak
Odd Form Handling
Curing
In situ
Mass curing
Heat
UV
Epoxy application
Writing
Jetting
Pin Transfer
Dipping
Segments
Eutectic
Sintering
90° Flip
Flip Chip
Direct Attach
Scalability
Cleanliness ISO 4

### Performance

- X/Y placement accuracy: ± 7 µm @ 3s
- Theta placement accuracy: ± 0.15° @ 3s

### Bond Heads

- Standard bond head 0° - 360° rotation
- Heated bond head (optional)

### Footprint

- L x D x H: 1160 mm x 1225 mm x 1800 mm
- Statistics
- Uptime > 98 %
- Yield > 99.95 %

### Wafer

- Die size Die attach: 0.17 mm - 50 mm
- Die thickness: 0.05 mm - 7 mm
- Wafer size: 2" - 12" (50 mm - 300 mm)

### Chip Trays

- Waffle pack / Gel-Pak® 2" x 2" and 4" x 4"
- JEDEC tray on request
- Substrates and Carriers

### Substrate working range

- 13" x 8"(325 mm x 200 mm)